



# 江西省晶能半导体有限公司

JiangXi LatticePower Semiconductor Corporation

## 产 品 规 格 书

### Specification

产品名称 Product Name:	<u>Infrared Chip LED</u>
产品型号 Product Type:	<u>IR953C-A01-2D</u>
客 户 Client name:	<u></u>
客户料号 Client P/N:	<u></u>
版 本 号 Version No.:	<u>Y02</u>
日 期 Sending Date:	<u>2022.07.15</u>

客户承认栏 Client Approval	
核准 Approval	确认 Audit

制定 Confirmation: \_\_\_\_\_ 审核 Approval: \_\_\_\_\_

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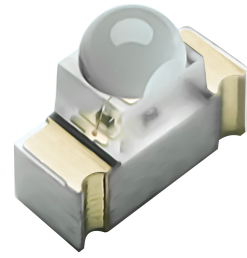
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## 1、特点 Features

- ◆ 侧视角 LED  
Side View LED
- ◆ 窄视角  
Narrow viewing angle
- ◆ 低电压  
Low forward voltage
- ◆ 适用于回流焊  
Suitable for reflow soldering
- ◆ 无铅  
Pd free
- ◆ 符合 RoHS 标准  
RoHS compliant
- ◆ IPC / JEDEC J-STD-020C: MSL-3



## 2、描述 Description

- ◆ IR953C-A01-2D 是一种微型 SMD 封装的红外发射二极管，采用球形顶视图透镜的透明塑料成型,该器件与硅光电二极管和光电晶体管光谱匹配。

IR953C-A01-2D is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens.The device is spectrally matched with silicon photodiode and phototransistor.

## 3、应用 Applications

- ◆ 红外应用系统  
Infrared applied system

## 4、性能 Performance

### a) 极限参数 Maximum Ratings (Ta =25 °C, unless specified otherwise)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
反向电压 Reverse Voltage	V <sub>R</sub>	5	V
正向恒流电流 DC Forward Current	I <sub>F</sub>	50	mA
正向峰值电流*1 Peak Forward Current	I <sub>FP</sub>	1000	mA
消耗功率 Power Dissipation	P <sub>d</sub>	100	mW
工作温度 Operating Temperature Range	T <sub>otr</sub>	-40~85	°C
存储温度 Storage Temperature	T <sub>stg</sub>	-40~100	°C
ESD (人体模式) ESD Human Body Mode	HBM	2000	V

备注 Notes:

\*1 : I<sub>FP</sub> Conditions--Pulse Width  $\leq$  50  $\mu$  s and Duty  $\leq$  1%

**b) 光电参数 Electro-Optical Characteristics (Ta =25 °C, unless specified otherwise)**

项目 Item	符号 Symbol	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit	条件 Condition
辐射强度 Radiant Intensity	I <sub>E</sub>	14.5	28	----	mw/sr	I <sub>F</sub> =20mA
		50	----	----		I <sub>F</sub> =70mA, T <sub>p</sub> =20ms
峰值波长 Peak Wavelength	λ <sub>p</sub>	----	940	----	nm	I <sub>F</sub> =20mA
顺向电压 Forward Voltage	V <sub>F</sub>	----	1.25	1.5	V	I <sub>F</sub> =20mA
		----	----	1.6		I <sub>F</sub> =70mA, T <sub>p</sub> =20ms
视角 Viewing Angle	2θ1/2	----	18	----	°	I <sub>F</sub> =20mA
光谱带宽 Spectral Bandwidth	Δλ	----	35	----	nm	I <sub>F</sub> =20mA
反向电流 Reverse Current	I <sub>R</sub>	----	----	10	uA	V <sub>R</sub> =5V

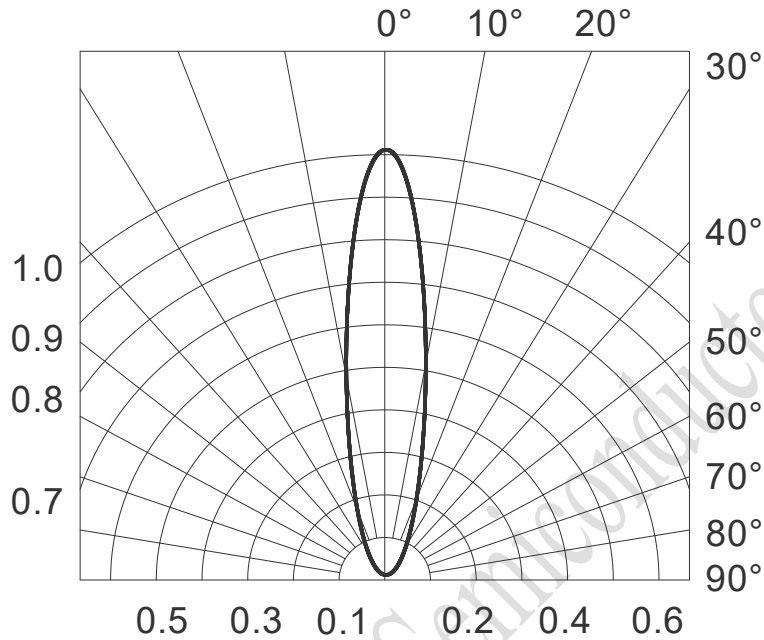
备注 Notes:

- ◇ 辐照强度公差均为:±15%。  
Tolerance of radiant intensity: ±15%.
- ◇ 峰值波长公差均为: ±1nm。  
Tolerance of peak wavelength: ±1nm.
- ◇ 电压公差均为: ±0.1V。  
Tolerance of forward voltage : ±0.1V.

## 5、光电特性图 The Photoelectric Characteristics Graph

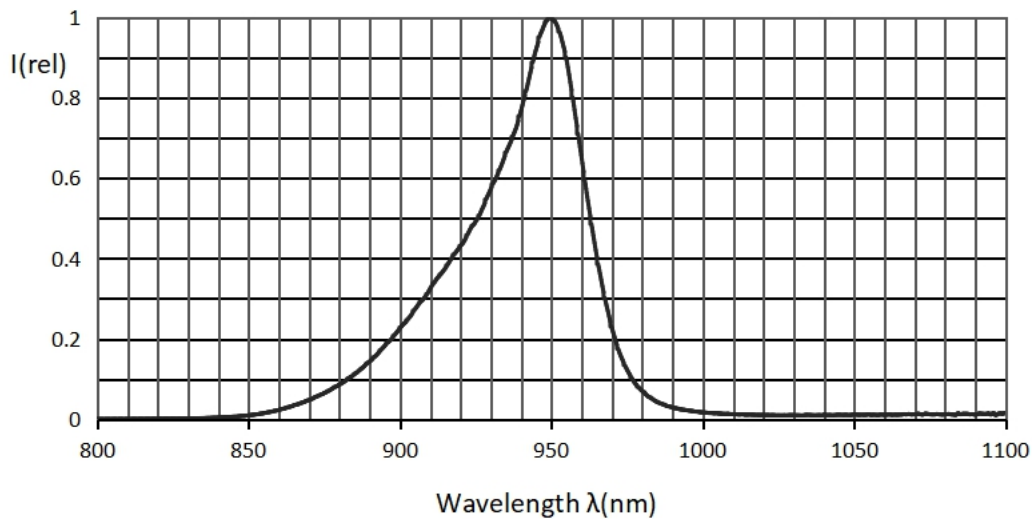
**Fig 1. 定向特性 / Directional Characteristics**

$I(\text{rel}) = f(\theta)$ ;  $T_a = 25^\circ\text{C}, I_f = 20\text{mA}$



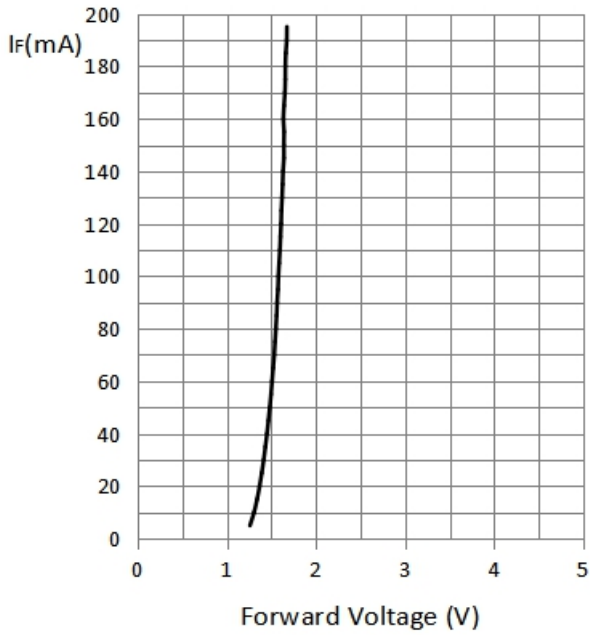
**Fig 2. 相对光谱 / Relative Spectral**

$I(\text{rel}) = f(\lambda)$ ;  $T_a = 25^\circ\text{C}, I_f = 20\text{mA}$



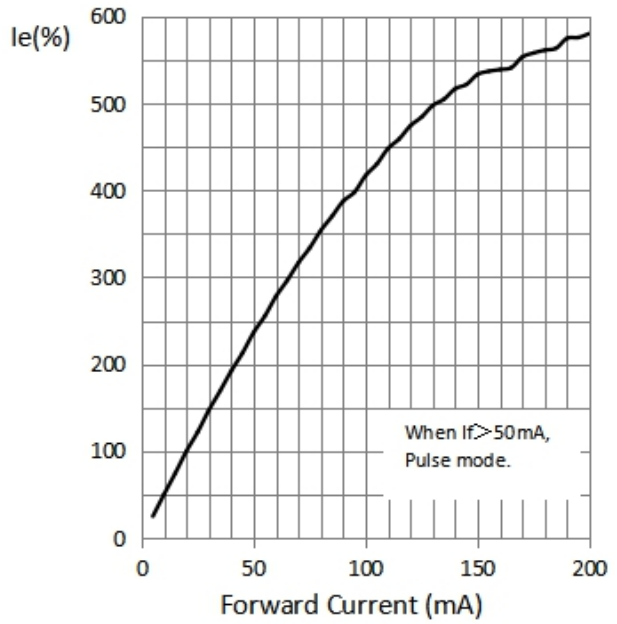
**Fig 3.正向电压/Forward Voltage**

$I_F = f(V); T_a = 25^\circ\text{C}.$



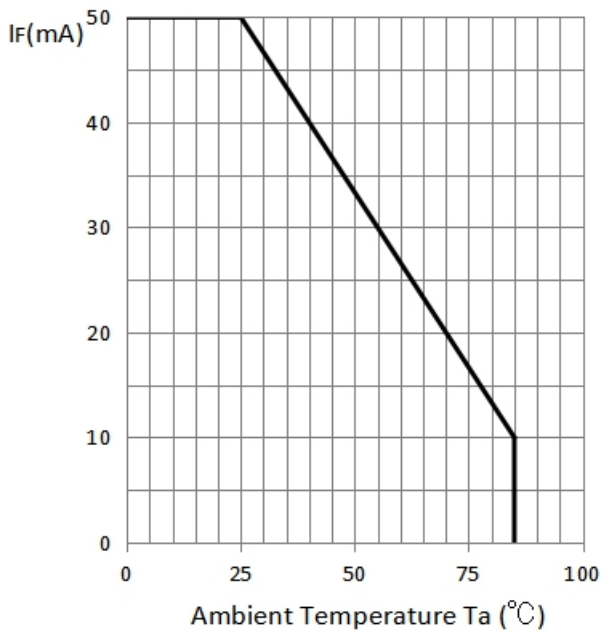
**Fig 4.辐射强度/Radiant Intensity**

$I_e / I_e(20\text{mA}) = f(I_F); T_a = 25^\circ\text{C}.$



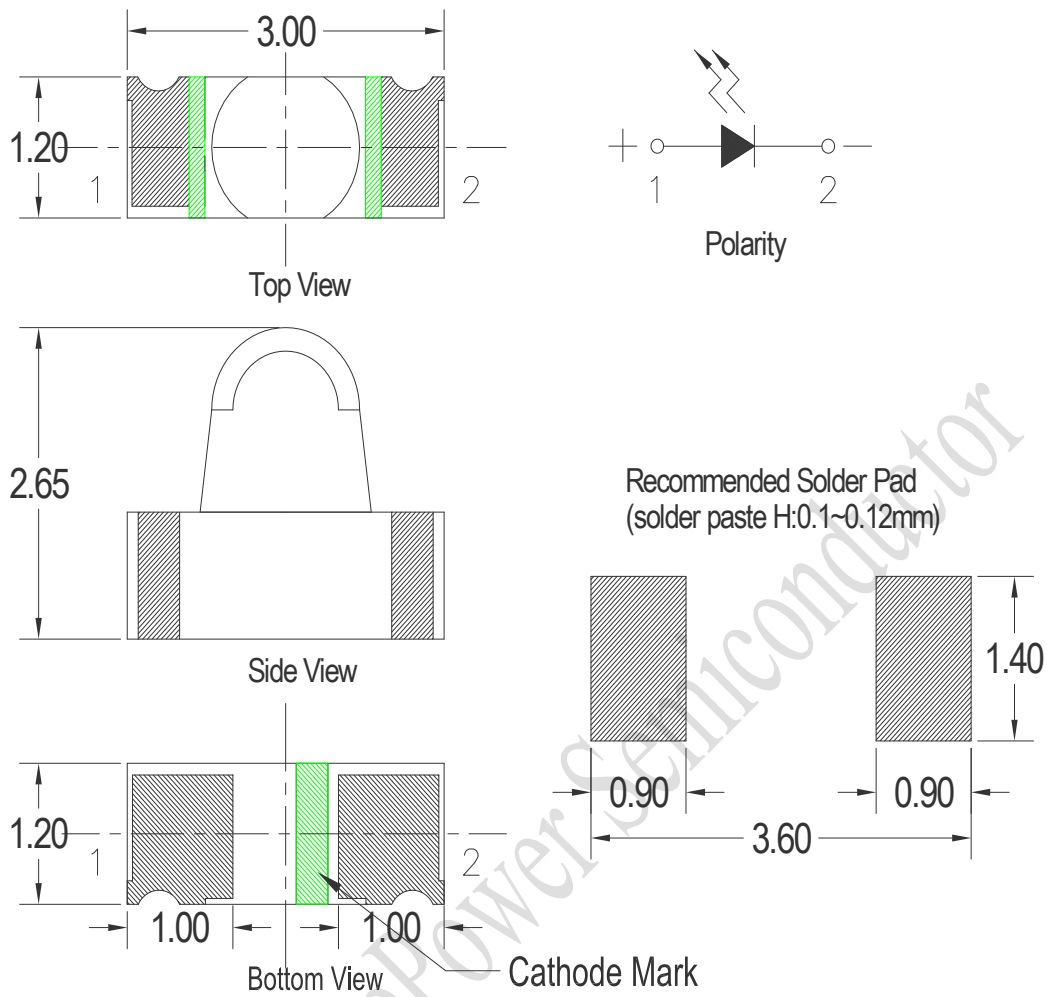
**Fig 5.最大正向电流/Max. Permissible Forward Current**

$I_{F,max} = f(T_a);$



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## 6、产品尺寸 Product Dimensions



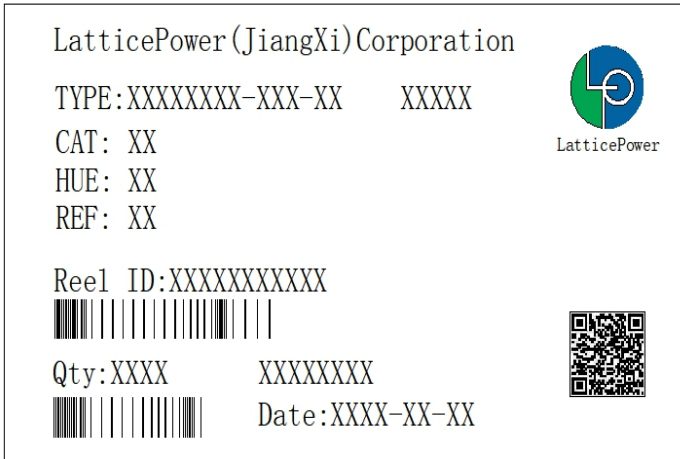
### 备注 Notes:

- ◇ 所有尺寸均以 mm 为单位  
All dimensions are in millimeters
- ◇ 尺寸未按照公差 $\pm 0.15\text{mm}$  标记的，按照图纸标记  
Size is not marked in accordance with tolerance  $\pm 0.15\text{mm}$  and dimension tolerances in accordance with drawings



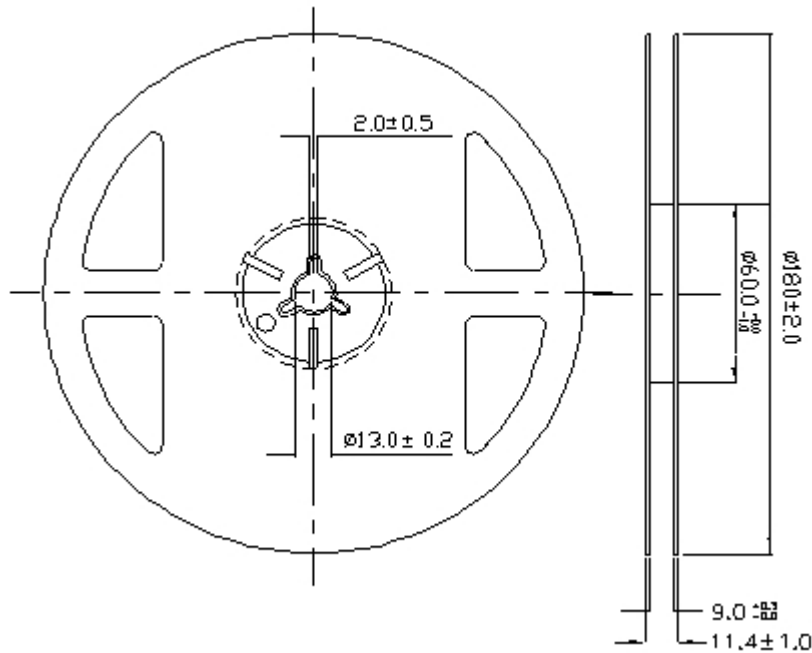
## 7、防潮包装材料 Moisture Resistant Packing Materials

### a) 标签说明 Label Explanation

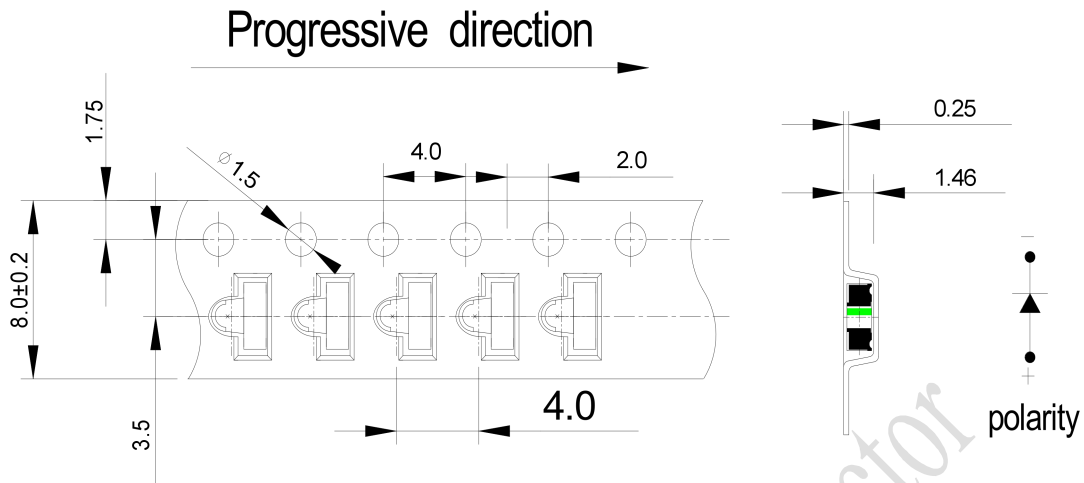


- TYPE: Product Type
- CAT: Rank
- HUE: Peak Wavelength
- REF: Reference
- Reel ID.: Reference
- QTY: Packing Quantity

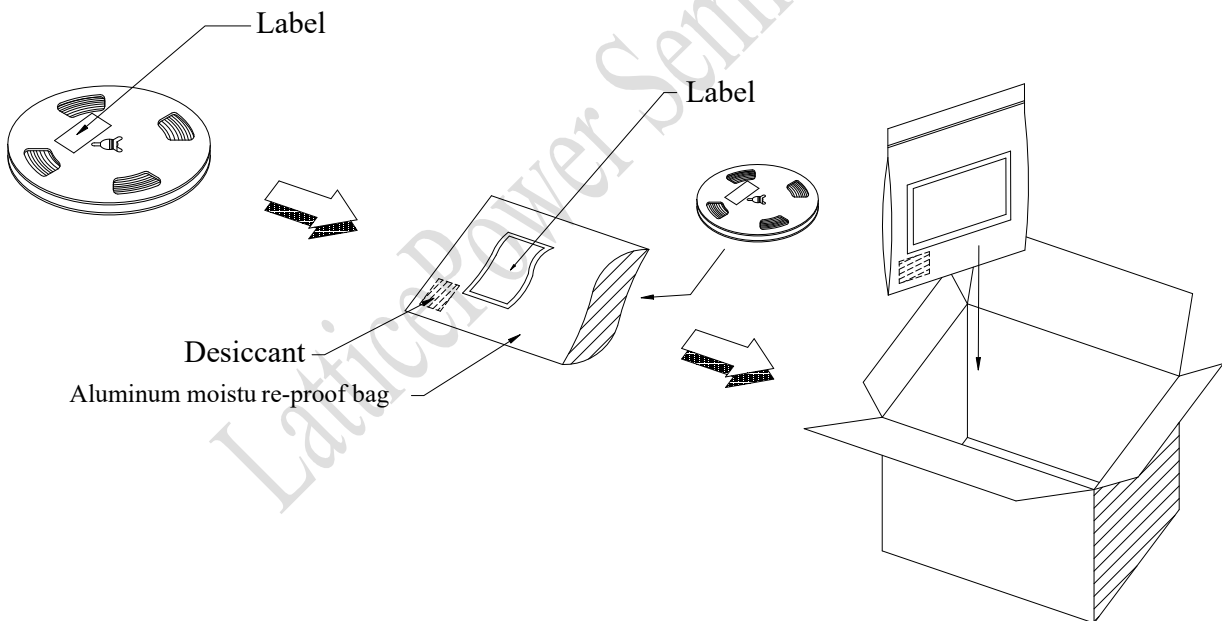
### b) 卷轴尺寸 Reel Dimensions



### c) 包装数量规格 Packing Quantity Specification



### d) 防潮包装工艺 Moisture Resistant Packing Process



#### 备注 Notes:

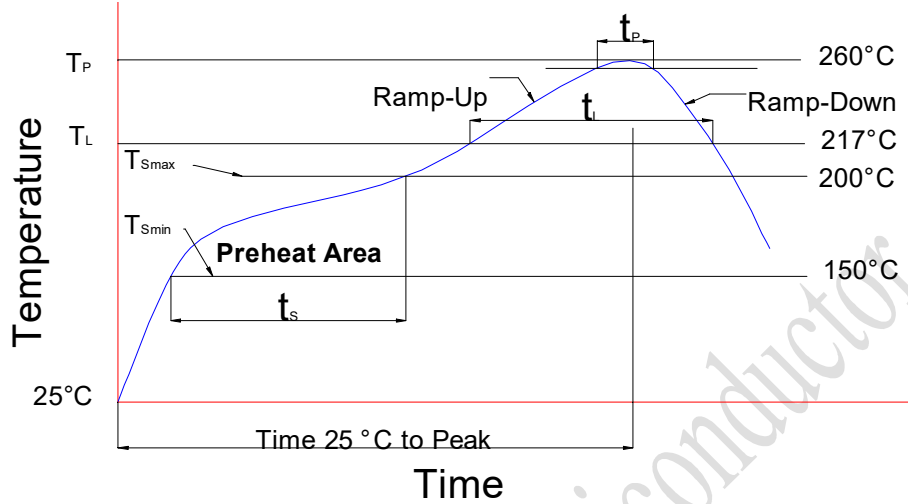
- ◇ 未标注的公差均为 $\pm 0.1$ mm, 单位为 mm. Tolerance unless mentioned is  $\pm 0.1$ mm, Unit = mm
- ◇ 卷轴包装 2000pcs Reel:2000pcs.
- ◇ 当包装与标签有特殊要求时,以客户需求为准。  
When there are special requirements for packaging and labeling, customer demand prevails.
- ◇ 当卷轴由于工作中断而重绕时,载带上压力不应超过 10N, 否则 LED 可能会粘在盖带上  
When the tape is rewound due to work interruptions, no more than 10N should be applied to the embossed carrier tape.  
The LEDs may stick to the cover tape.

## 8、焊接条件 Soldering Condition

### a) 回流焊 Reflow soldering

➤ 无铅回流焊温度曲线

Pb-free solder temperature profile



根据 EDEC-J-STD-020E 内容，参考以下内容。

Compatible with the JEDEC-J-STD-020E, using the parameters listed below.

特制参数 Profile Feature	无铅焊料 Lead-Free Solder
平均上升速率 (T <sub>smax</sub> 至 T <sub>p</sub> ) Average Ramp-Up Rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/sec max.
预热: 温度最小值 (T <sub>smin</sub> ) Preheat: Temperature Min (T <sub>smin</sub> )	150
预热: 最高温度 (T <sub>smax</sub> ) Preheat: Temperature Max (T <sub>smax</sub> )	200
预热: 时间 (t <sub>smin</sub> 到 t <sub>smax</sub> ) Preheat: Time (t <sub>smin</sub> to t <sub>smax</sub> )	60-180 secs
回流温度 (T <sub>L</sub> ) Time Maintained Above: Temperature (T <sub>L</sub> )	217°C
回流时间 (t <sub>L</sub> ) Time Maintained Above: Time (t <sub>L</sub> )	60-150 secs
峰值/分类温度 (T <sub>p</sub> ) Peak/Classification Temperature (T <sub>p</sub> )	255 ± 5°C
实际峰值温度 (t <sub>p</sub> ) 在 5°C 以内的时间 Time Within 5°C of Actual Peak Temperature (t <sub>p</sub> )	30 secs max.
降低速率 Ramp-Down Rate	4°C/sec max.

- 回流焊不应做两次以上。  
Reflow soldering should not be done more than two times.
- 在焊接升温过程中,不要挤压 LED。  
When soldering, do not put stress on the LED during heating.
- 在焊接后,不要使电路板翘曲。  
After soldering, do not warp the circuit board.

## b) 手工焊接 Hand Soldering

- 推荐使用功率低于 20W 的烙铁,焊接时烙铁的温度必须保持在 350°C 以下,且每个电极只能进行一次焊接,每次焊接的持续时间不得超过 3 秒。  
If manual soldering is necessary used, the power of less than 20W is recommended. The temperature of the iron must be kept at below 350° C, with soldering time within 3 seconds and each electrode can be only soldered at one time

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## 9、可靠性 Reliability

### a) 测试和结果 Tests and Results

测试项目 Test Item	标准 Reference Standard	测试条件 Test Conditions	测试周期 Test Duration
回流焊 Solder ability(Reflow Soldering)	JEITA ED-4701 300 302	Tsld=255±5°C,5sec,Lead-free Solder	3 times
高低温循环 Temperature Cycle	JEITA ED-4701 100 105	-40°C(30min)~85°C(30min)	300cycles
冷热冲击 Thermal Shock	MIL-STD-202G-107G-A	-40°C(15min)~85°C(15min)/ Transfer time <20sec	300cycles
低温存储 Low Temperature Storage	JEITA ED-4701 100 202	T <sub>A</sub> =-40°C	1000H
高温存储 High Temperature Storage	JEITA ED-4701 100 201	T <sub>A</sub> =85°C	1000H
高温高湿寿命 Temperature Humidity Operating Life	JEITA ED-4701 100 103 JESD22-A108	T <sub>a</sub> =85°C, RH=85%, I <sub>F</sub> = 10mA	1000H
高温寿命 High Temperature Life	JESD22-A108	T <sub>a</sub> =85°C, I <sub>F</sub> = 10mA	1000H
静电放电测试 Electrostatic Discharge Test	JESD22-A114	Human body model : 2000 V	

### b) 失效标准 Failure Criteria

Criteria #	Items	Conditions	Failure Criteria
#1	Forward Voltage (V <sub>F</sub> )	I <sub>F</sub> =20mA	> Initial value×1.1 or < Initial value×0.9
	Reverse Current (I <sub>R</sub> )	V <sub>R</sub> =5V	> 10uA
	Radiant Intensity(mw/sr)	I <sub>F</sub> =20mA	< Initial value×0.7
	Peak Wavelength (nm)	I <sub>F</sub> =20mA	> Initial value+2nm or <Initial value-2nm
#2	Solderability	-	Less than 90% solder coverage

## 10、注意事项 Cautions

### a) 过流保护 Over-current-proof

- 客户必须应用电阻进行保护，否则轻微的电压偏移会导致大电流变化（会发生烧坏）。  
Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### b) 存储 Storage

- 开封前，LED 需存放在温度不高于 30°C,湿度不高于 60%RH 的环境中,应在一年内用完。  
The LED should be stored in the environment of temperature<30°C and humidity<60% RH before opening the package,should be used within a year.
- 开包后建议在 24 小时内过完回流焊，车间条件≤30°C/60%RH。  
After opening the package, it is recommended to finish the reflow within 24 hours. The workshop conditions are ≤30°C/60%RH.
- 如果吸湿剂或包装失效，或者 LED 已超出存放时间,应使用如下条件进行烘烤。  
烘烤处理: 60±5°C,至少 24 小时以上。  
If the moisture absorbent material has faded away or the LED have exceeded the storage time, baking treatment should be performed using the following conditions.  
Baking treatment : 60±5°C for Min. 24 hours.
- 防止静电死亡，手动操作需要戴橡胶手套并佩戴静电环。  
Prevent electrostatic killed, Manual operation is required to wear rubber gloves and wear electrostatic ring.

### b) 清洗 Cleaning

- 通常，LED 不建议对部件进行湿式清洁处理，因为封装不是密封的。  
In general, LED does not recommend a wet cleaning process for component as the package is not hermetically sealed.
- 由于采用开放式设计，所有类型的清洁液都可能渗透到封装中，导致 LED 退化或完全失效。  
Due to the open design, all kind of cleaning liquids can infiltrate the package and cause a degradation or a complete failure of the LED.

### c) 操作注意 Handling Precautions

- 在处理过程中，还应注意确保组件顶面没有压力。  
During the handling, care should be taken as well to ensure no pressure on the top surface of component.
- 应避免使用所有类型的尖锐物体（例如镊子，指甲等），以防止对树脂造成压力，因为这会导致部件损坏。  
All types of sharp objects(e.g. forceps, fingernail, etc) should be avoided in order to prevent stress to the resin, since this can lead to damage of the component.

## 11、文件履历表 Document Resume

序号	变更日期	变更人	版本	变更内容
01	2021.9.8	丁焕	Y00	研发新制定初版.
02	2022.6.13	丁焕	Y01	增加辐射强度规格下限和典型值, 修改包装数量为 2000pcs
03	2022.07.15	丁焕	Y02	修改辐射强度公差

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